



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

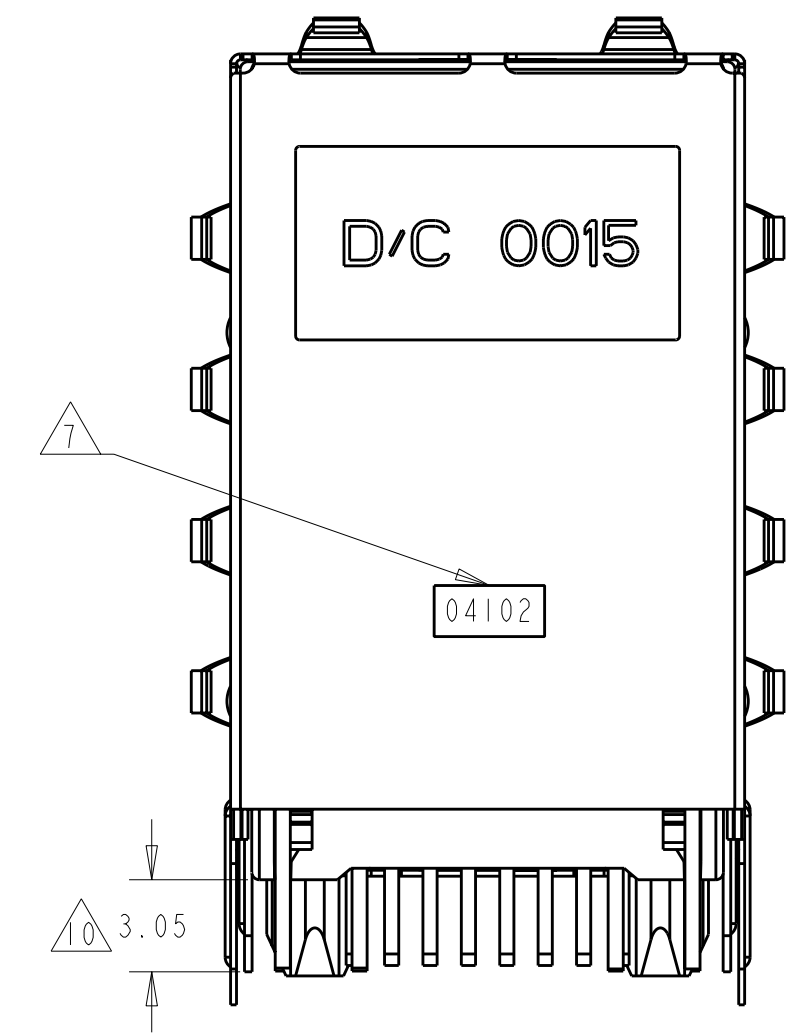
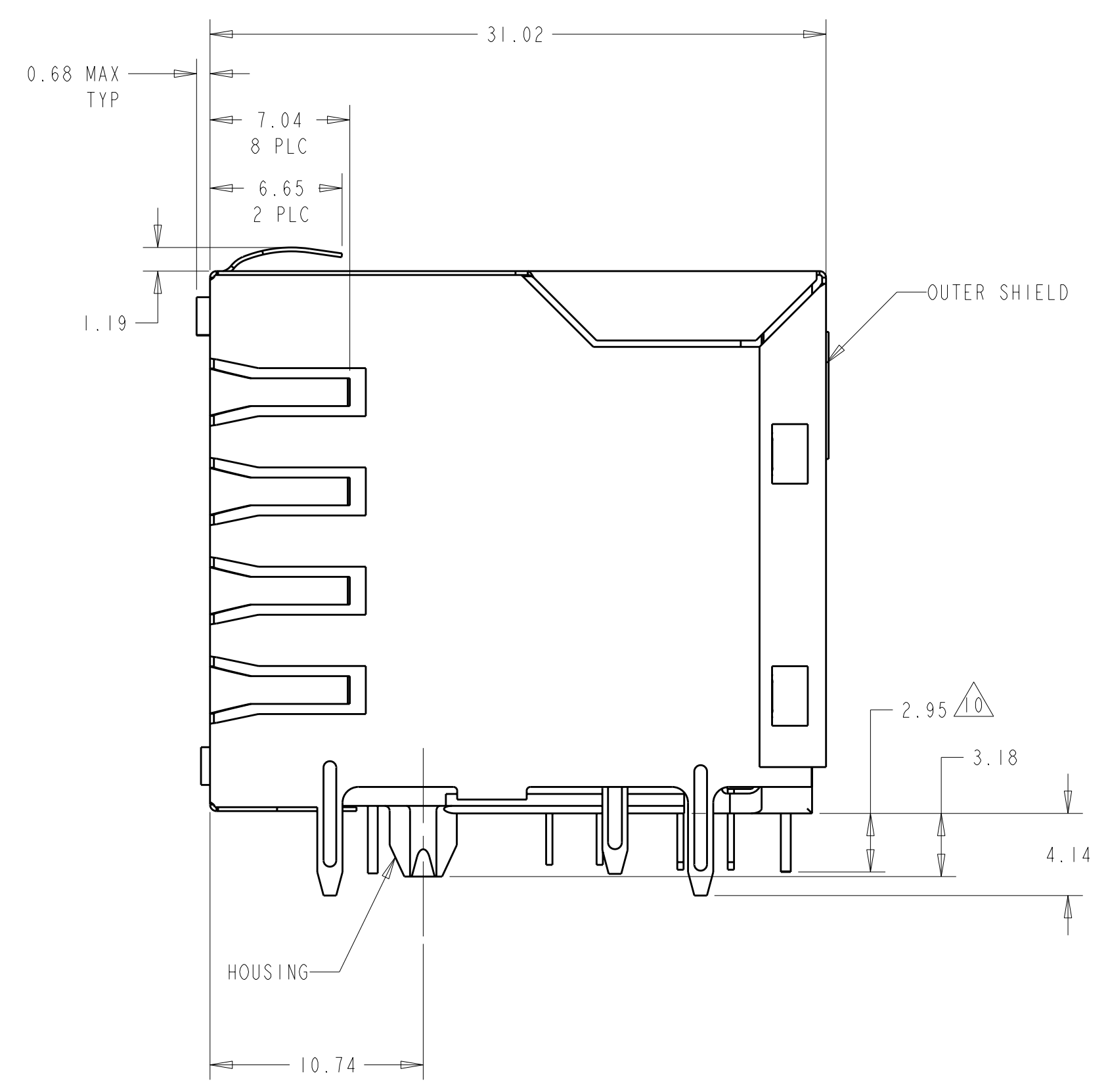
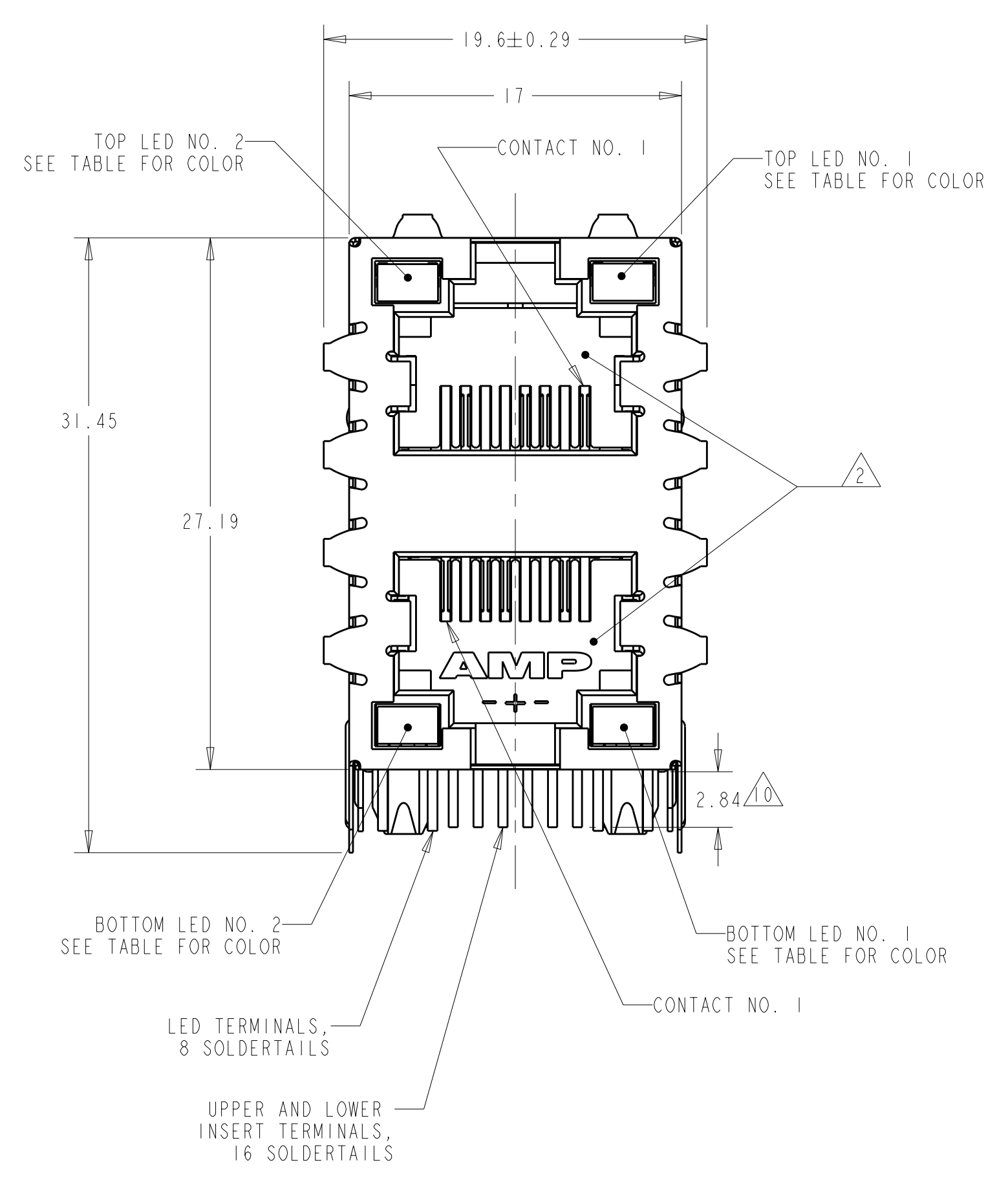
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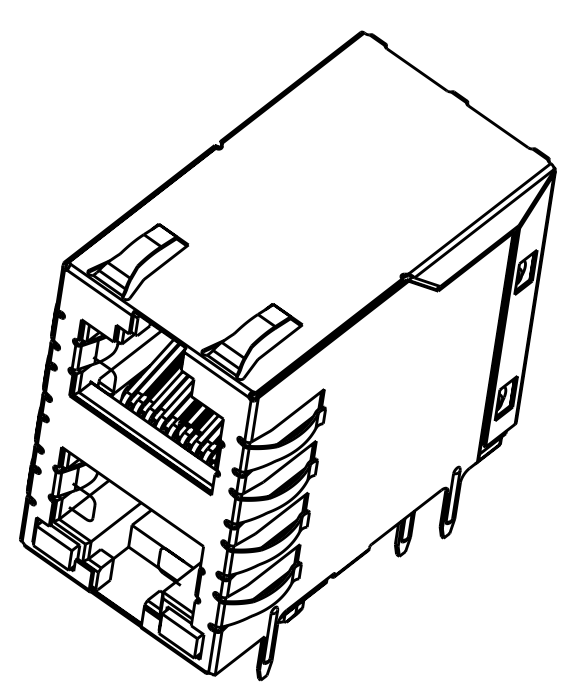
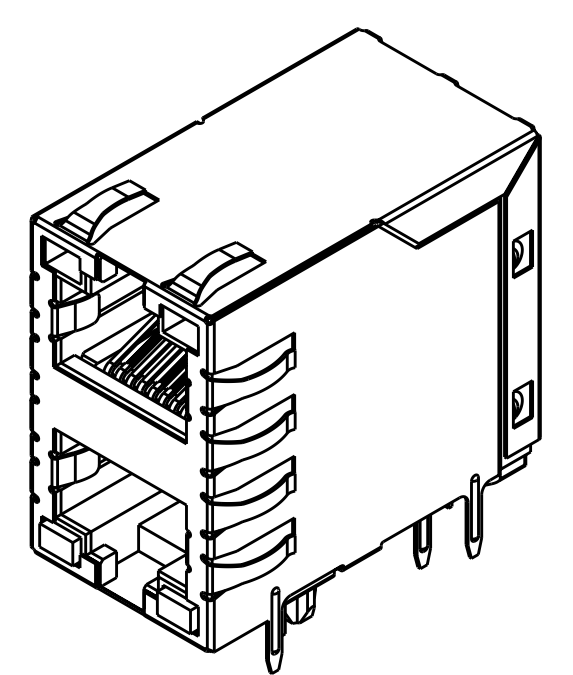
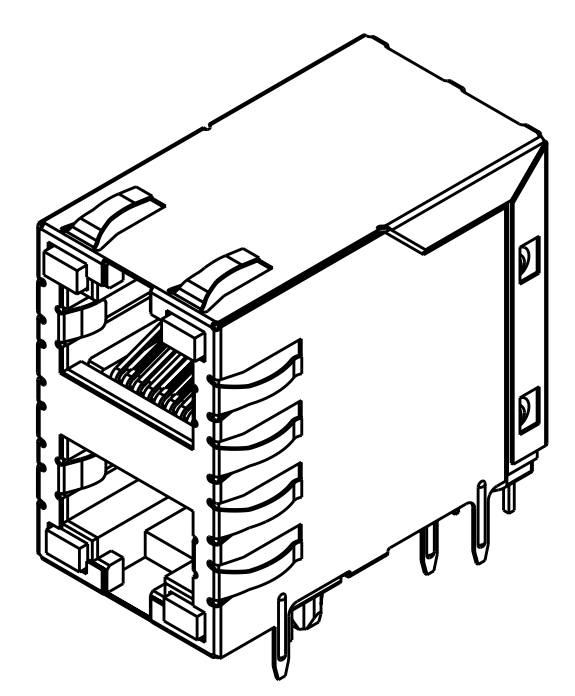
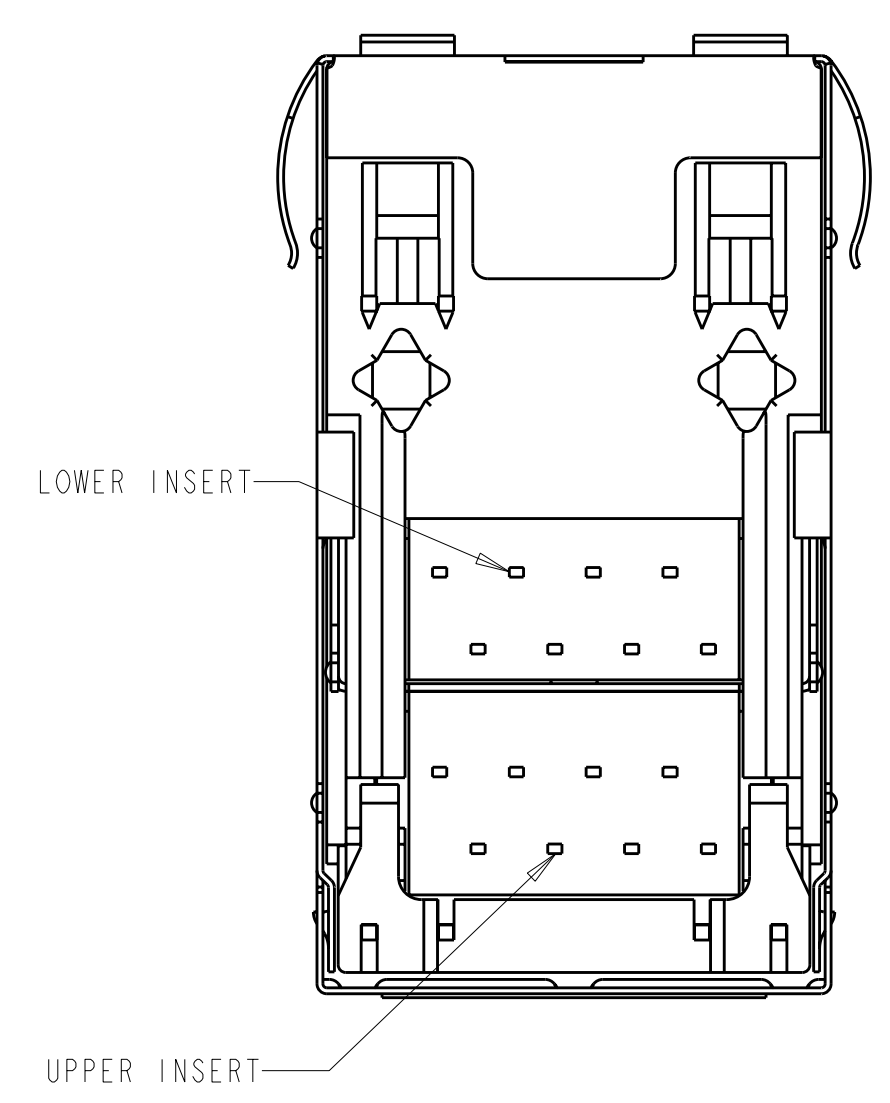


THIS DRAWING IS A CONTROLLED DOCUMENT
PART NO. 6368011



- MATERIAL: HOUSING - PBT POLYESTER, BLACK, UL 94V-0.
TERMINALS - 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27um MINIMUM THICK HARD GOLD IN LOCALIZED MATING INTERFACE AND 3.81um MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27um MINIMUM THICK NICKEL UNDERPLATE.
SHIELD - 0.196 THICK COPPER ALLOY PLATED WITH 1.27 um [0.00050] MINIMUM NICKEL AND 2.03 um [0.00080] MINIMUM HOT TIN DIP ON PCB GROUND TABS..
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 X 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 um THICK Sn/Cu OVER 2.03 um THICK Ag OVER 1.02 THICK Cu OVER 3.56 um THICK Ni OVER 1.02 um Cu UNDERPLATE

- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- SUGGESTED OPERATING CURRENT FOR THE LED IS 20mA. GREEN/ORANGE BI-COLOR LEDS ON 6368011-4 AND 1-6368011-0 WILL EMIT GREEN LIGHT ON FORWARD BIAS CURRENT AND ORANGE LIGHT ON REVERSE BIAS CURRENT. GREEN/RED BI-COLOR LEDS ON 6368011-9 AND 1-6368011-0 WILL EMIT GREEN LIGHT ON FORWARD BIAS CURRENT AND RED LIGHT ON REVERSE BIAS CURRENT. GREEN/YEL BI-COLOR LEDS ON 1-6368011-1 WILL EMIT GREEN LIGHT ON FORWARD BIAS CURRENT AND YELLOW LIGHT ON REVERSE BIAS CURRENT.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- USE NO. 30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- HM-15 LUBE APPLIED TO THE GOLD PLATED AREA OF THE TERMINALS ON 6368011-8 ONLY.
- DATE CODE LOCATED ON REAR OF PART APPROX AS SHOWN: FIRST 2 DIGITS ARE LAST 2 DIGITS OF YEAR, SECOND 2 DIGITS ARE MANUFACTURING WORK WEEK, LAST DIGIT IS DAY OF WEEK, WITH SUNDAY=1.
- THE PART NUMBER IS PRELIMINARY.
- OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- GROUND PIN AND ALL SIGNAL PINS' LENGTH SHOULD BE 4.06 MM EXCEPT OUTER SHIELD THIS REQUEST IS ONLY FOR PART 1-6368011-4



9 OBSOLETE

9 OBSOLETE

3.44 MAX	GREEN	GREEN	GREEN	GREEN	1-6368011-5
4.14	GREEN	YELLOW	GREEN	YELLOW	1-6368011-4
4.14	GREEN	YELLOW	N/A	N/A	1-6368011-3/8
4.14	GREEN/YELLOW	GREEN/YELLOW	GREEN/YELLOW	GREEN/YELLOW	1-6368011-0
4.14	GREEN/ORANGE	GREEN/ORANGE	GREEN/RED	GREEN/RED	1-6368011-1
4.14	GREEN/RED	GREEN/RED	GREEN/RED	GREEN/RED	6368011-9
4.14	YELLOW	GREEN	YELLOW	GREEN	6368011-8/6
4.14	GREEN	ORANGE	N/A	N/A	6368011-7
4.14	GREEN	GREEN	YELLOW	GREEN	6368011-6
4.14	YELLOW	GREEN	YELLOW	GREEN	6368011-5
4.14	GREEN/ORANGE	GREEN/ORANGE	GREEN/ORANGE	GREEN/ORANGE	6368011-4
4.14	GREEN	YELLOW	GREEN	YELLOW	6368011-3
4.14	YELLOW	GREEN	GREEN	YELLOW	6368011-2
4.14	GREEN	GREEN	GREEN	GREEN	6368011-1
DIM A	BOTTOM LED NO. 2	BOTTOM LED NO. 1	TOP LED NO. 2	TOP LED NO. 1	PART NUMBER

LOC
AA
DIST
22

DWN 13APR2005
Vic Slack/L.A.MAYER

CHK 13APR2005
J.WESTMAN

APVD 13APR2005
S.FLICKINGER

MATERIAL SEE NOTE 1

HEAT TREAT -

TE Connectivity

NAME MODULAR JACK ASSEMBLY, STACKED,
2 X 1, 8 POSITION, SHIELDED,

SCALE 1:1 SIZE A1 DRAWING NO. 6368011 SHEET 1 OF 3 REV J

J	REV PER ECR-11-025824	13JAN2012	JJ	AC
P	LTR	REVISION RECORD	DATE	DWN

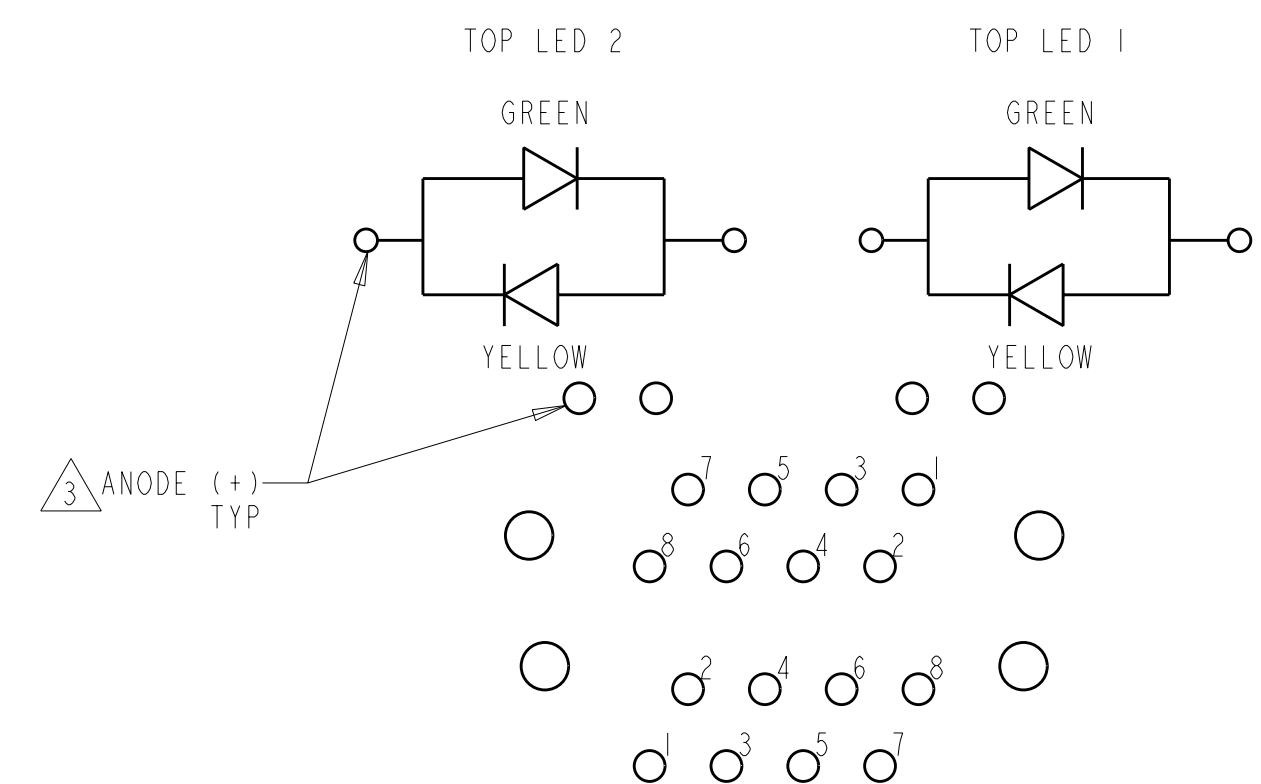
DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

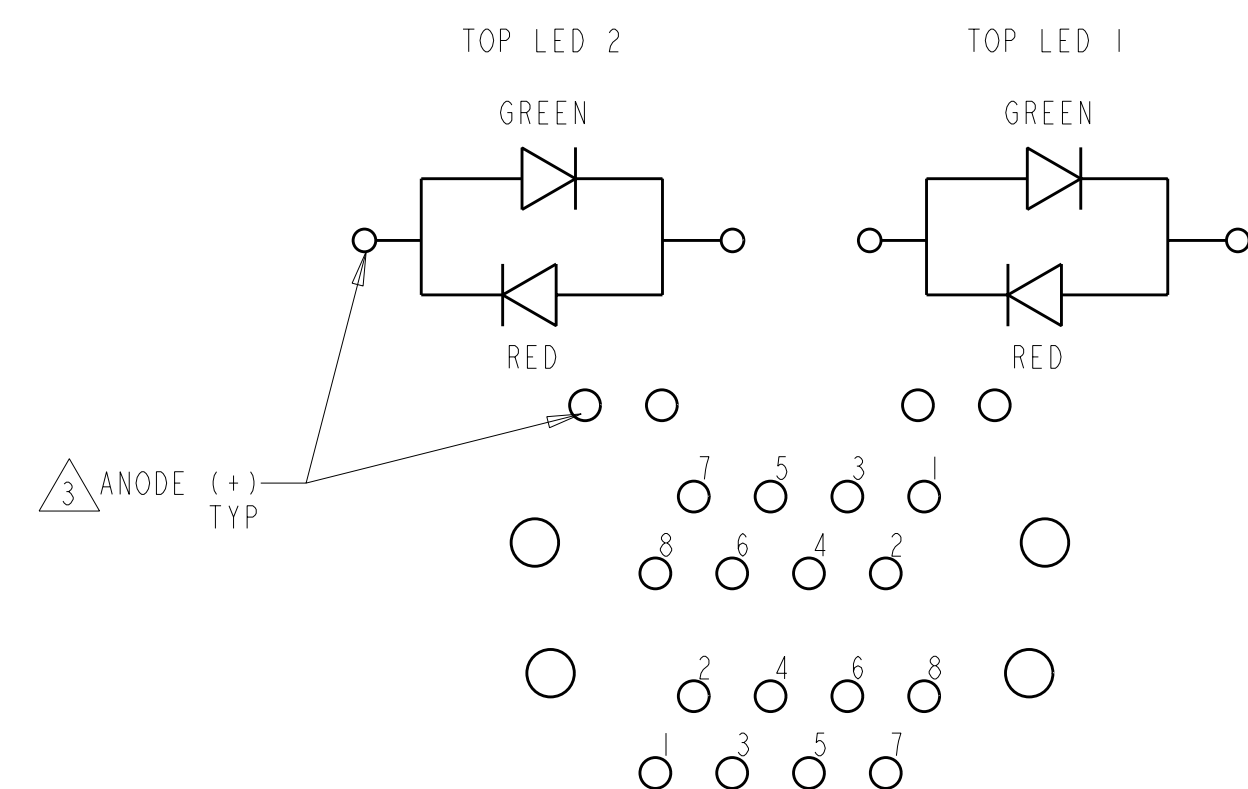
0 PLC	±
1 PLC	±0.25
2 PLC	±0.25
3 PLC	±0.25
4 PLC	±0.25

ANGLES: -

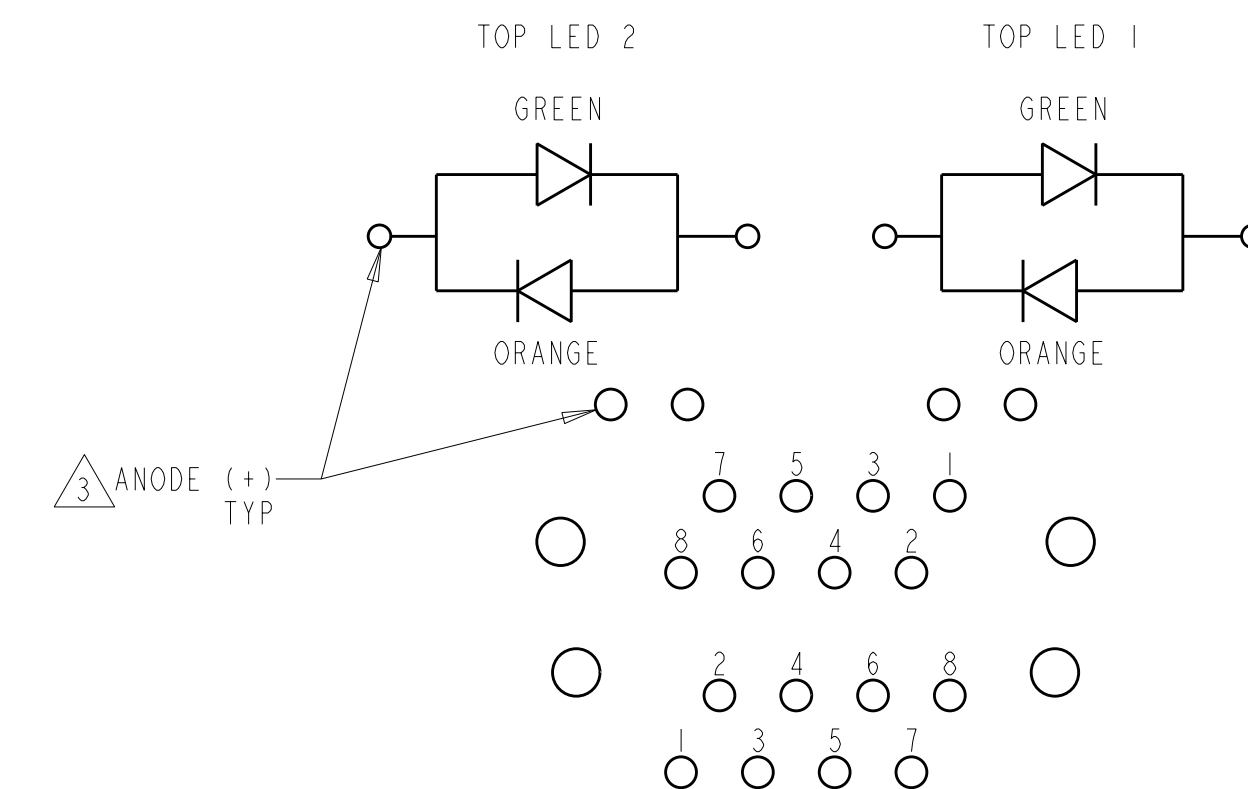
SURFACE TEXTURE: ✓



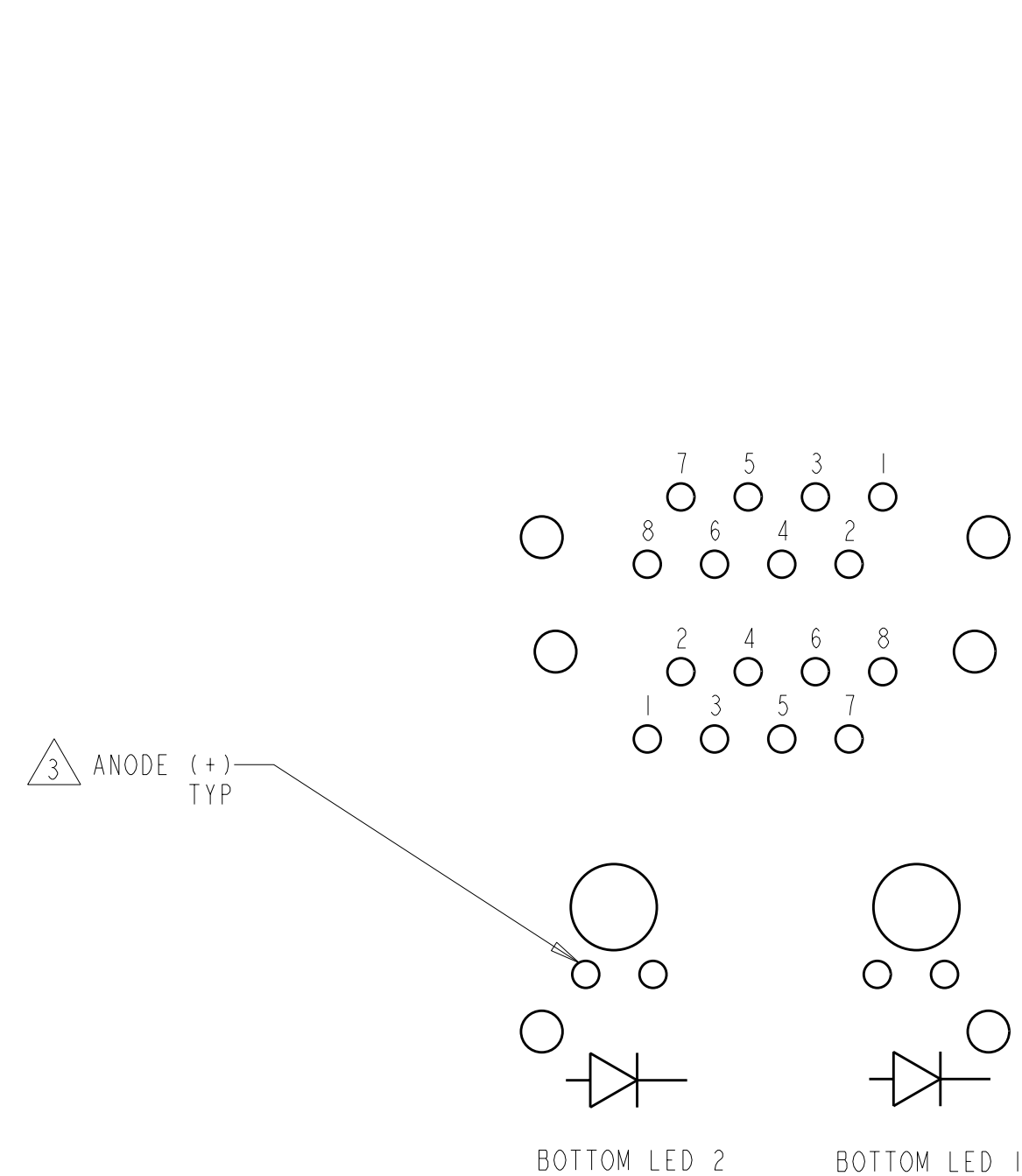
SCHEMATIC FOR 1-6368011-1
SCALE 4:1



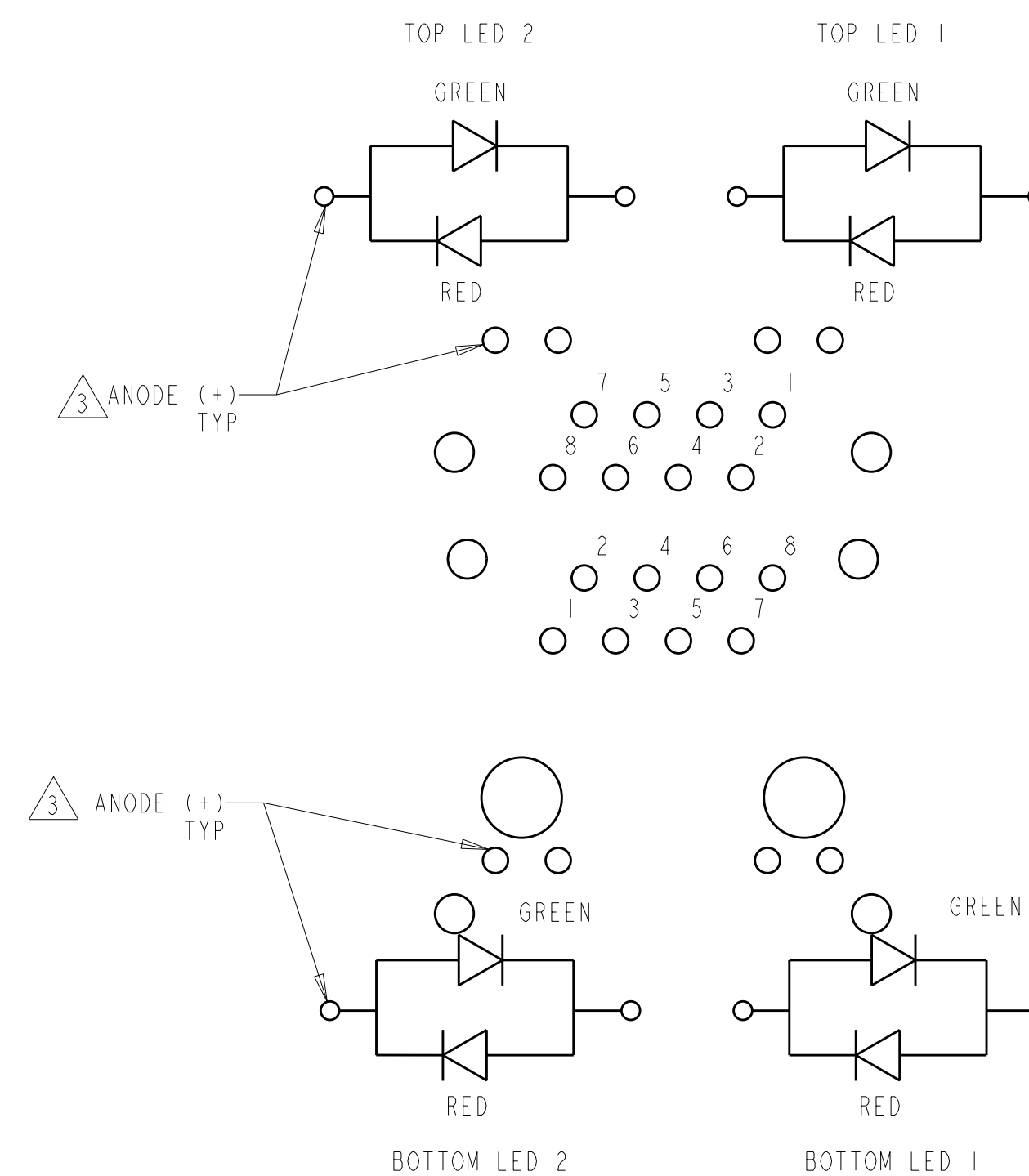
SCHEMATIC FOR 1-6368011-0
SCALE 4:1



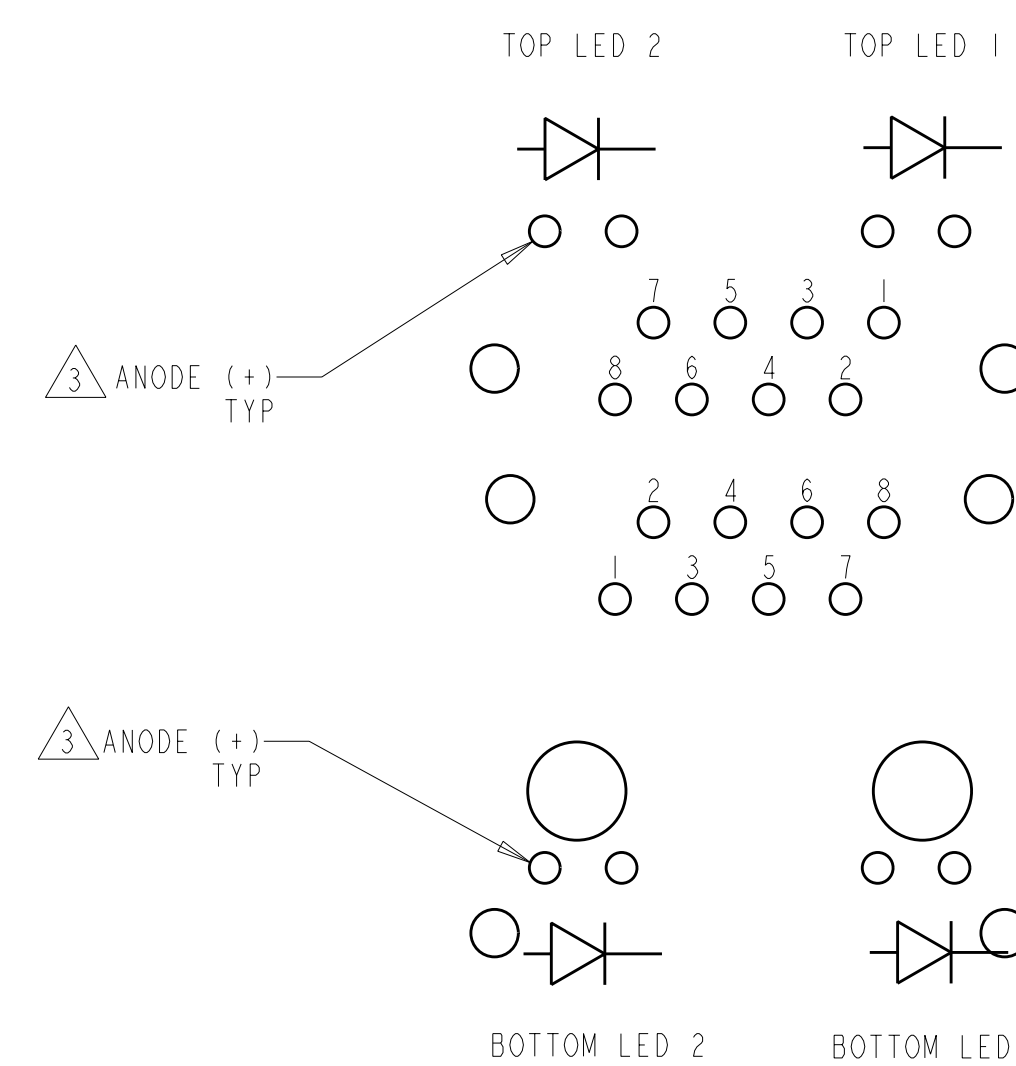
SCHEMATIC FOR 6368011-4
SCALE 4:1



SCHEMATIC FOR 6368011-7, 1-6368011-3



SCHEMATIC FOR 6368011-9
SCALE 4:1



SCHEMATIC FOR 6368011-1, -2, -3, -5, -6, -8, 14
SCALE 4:1

LOC	AA
DIST	22

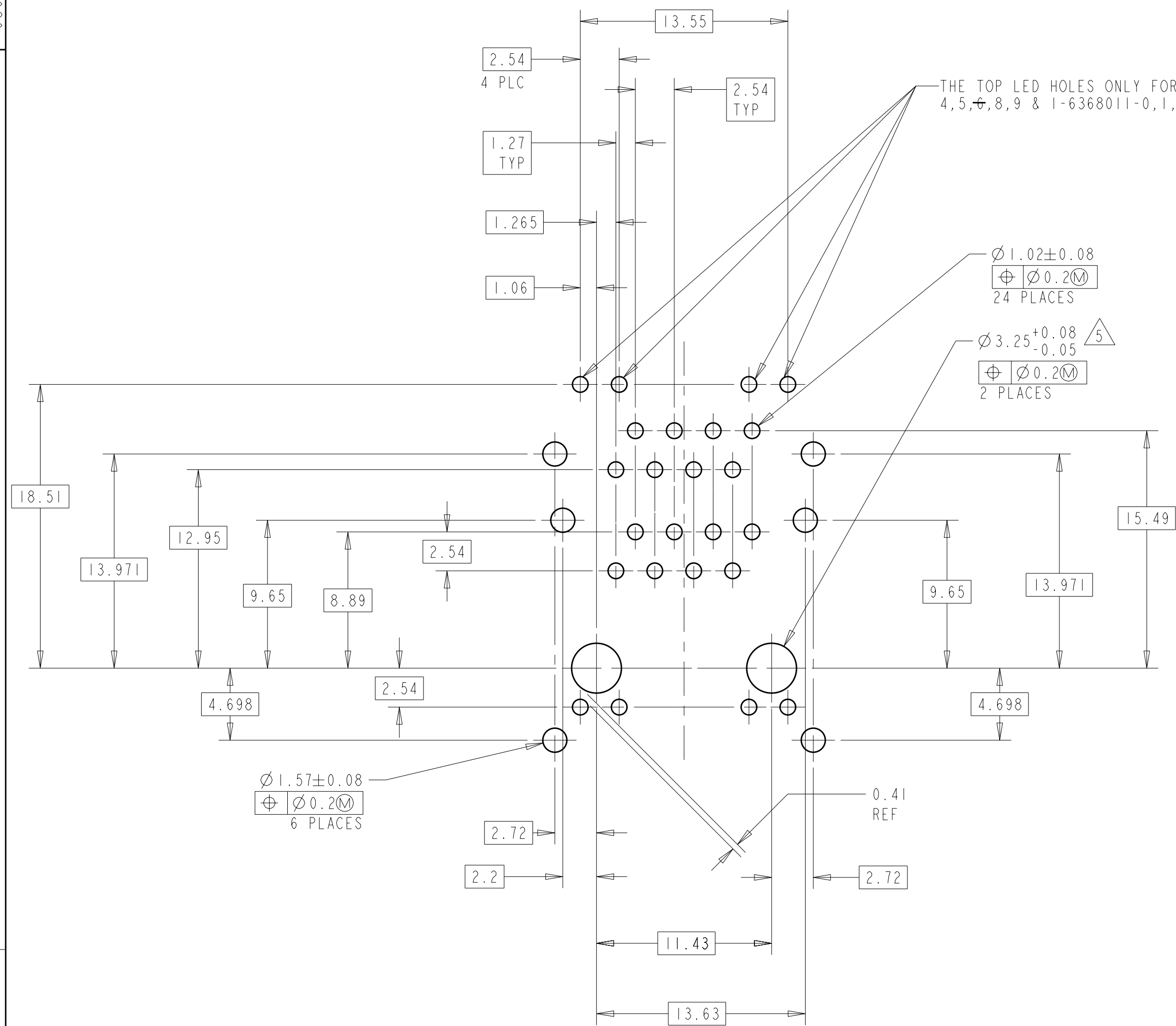
P	LTR	REVISION RECORD	DATE	DN	APVD
		SEE SHEET 1			

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:	
mm		0 PLC	±
		1 PLC	±0.25
		2 PLC	±0.25
		3 PLC	±0.25
		4 PLC	±
ANGLES:		SURFACE TEXTURE	
			✓

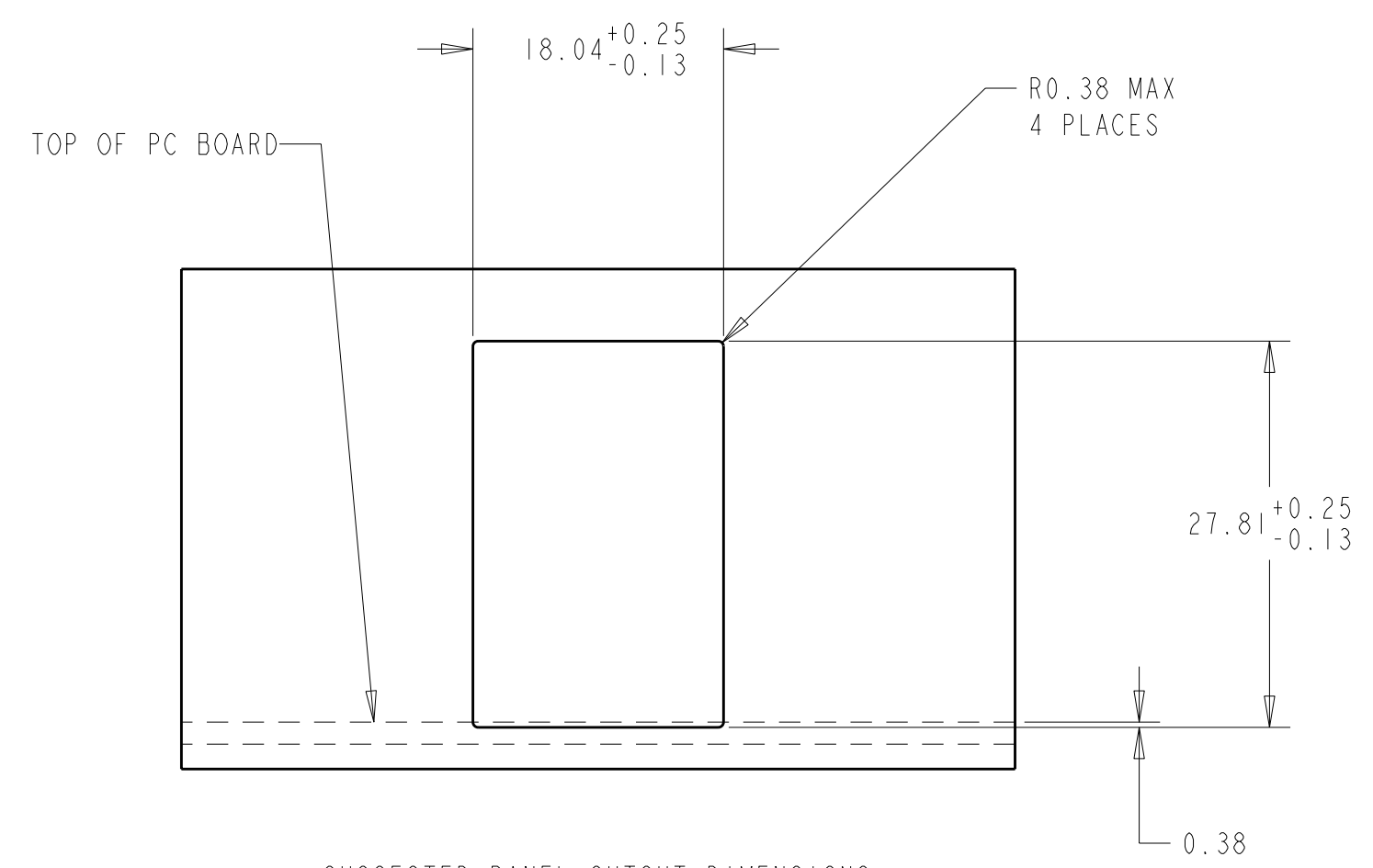
DNW	13APR2005	MATERIAL	SEE NOTE 1	HEAT TREAT	-
CHK	13APR2005				
APVD	13APR2005				
NAME: MODULAR JACK ASSEMBLY, STACKED, 2 X 1, 8 POSITION, SHIELDED,					
SCALE	1:1	SIZE	A1	DRAWING NO	6368011
SHEET	2	OF	3	REV	J

DWG NO 6368011

THIS DRAWING IS A CONTROLLED DOCUMENT



PC BOARD LAYOUT VIEWED FROM COMPONENT SIDE OF BOARD
SCALE 4:1



SUGGESTED PANEL CUTOUT DIMENSIONS
SCALE 2:1

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LOC	AA
DIST	22

P	LTR	REVISION RECORD	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:	
mm		0 PLC ±	1 PLC ±
		2 PLC ±0.25	3 PLC ±0.25
		4 PLC ±	
ANGLES:		SURFACE TEXTURE: $\sqrt{\quad}$	

DWN	13APR2005	MATERIAL	SEE NOTE 1	HEAT TREAT	-
CHK	Vic Slack/L.A.MAYER				
APVD	13APR2005				
	J.WESTMAN				
	S.FLICKINGER				
NAME: MODULAR JACK ASSEMBLY, STACKED, 2 X 1, 8 POSITION, SHIELDED.					
SCALE	1:1	SIZE	A1	DRAWING NO	6368011
SHEET	3	OF	3	REV	J